



### POWER FIELD EFFECT TRANSISTOR

### **GENERAL DESCRIPTION**

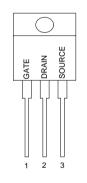
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

#### **FEATURES**

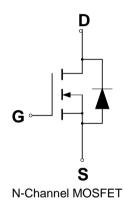
- Reduced Gate Charge
- ◆ Ultra Low On-Resistance Provides Higher Efficiency
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- ♦ I<sub>DSS</sub> and V<sub>DS</sub>(on) Specified at Elevated Temperature

#### PIN CONFIGURATION

#### TO-220/TO-220FP Front View



#### **SYMBOL**



### **ABSOLUTE MAXIMUM RATINGS**

Rating		Value	Unit
Drain to Current — Continuous		8.5	Α
- Pulsed		25.5	
Gate-to-Source Voltage — Continue	V <sub>GS</sub>	±30	V
Total Power Dissipation – TO220		190	W
– TO220FP		38	
Derate above 25℃ - TO220		1.43	W/°C
– TO220FP		0.36	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	$^{\circ}$
Single Pulse Drain-to-Source Avalanche Energy $-T_J = 25^{\circ}$ C		320	mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_{L} = 8A, L = 10mH, R_{G} = 25)$			
Thermal Resistance — Junction to Case -TO220		0.6	°CW
<ul> <li>Junction to Case -TO220FP</li> </ul>		3.5	
<ul> <li>Junction to Ambient -TO220, TO220FP</li> </ul>	JA	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	$^{\circ}\!\mathbb{C}$





## Power Field Effect Transistor

### ORDERING INFORMATION

Part Number	Package
GPT09N70GN220	TO-220
GPT09N70DGN220FP	TO-220 Full Package

<sup>\*</sup>Note: G : Suffix for Pb Free Product

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_J = 25^{\circ}C$ .

			GPT09N70			
Cha	racteristic	Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	700			V
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		I <sub>DSS</sub>			1	uA
$(V_{DS} = 700 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Forwa	rd	I <sub>GSSF</sub>			100	nA
$(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Reverse		$I_{GSSR}$			100	nA
$(V_{gsr} = 30 \text{ V}, V_{DS} = 0 \text{ V})$	$V_{DS} = 0 V$					
Gate Threshold Voltage		$V_{GS(th)}$	3		5	V
$(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V	$I_{GS} = 10 \text{ V}, I_D = 4.5 \text{A}) *$	R <sub>DS(on)</sub>			1.2	
Forward Transconductance (V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4.5A) *		<b>g</b> fs		7		S
Input Capacitance	(V - 25 V V - 0 V	C <sub>iss</sub>		1457.24		pF
Output Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz)	Coss		125.12		pF
Reverse Transfer Capacitance		C <sub>rss</sub>		5.95		pF
Turn-On Delay Time	$(V_{DD} = 350 \text{ V}, I_D = 9 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 9.1 ) *$	t <sub>d(on)</sub>		26.13		ns
Rise Time		t <sub>r</sub>		23.47		ns
Turn-Off Delay Time		t <sub>d(off)</sub>		39.5		ns
Fall Time		t <sub>f</sub>		16		ns
Total Gate Charge	// FCO.// L O.A	$Q_g$		29.3		nC
Gate-Source Charge	$(V_{DS} = 560 \text{ V}, I_D = 9 \text{ A},$	$Q_{gs}$		8.8		nC
Gate-Drain Charge	$V_{GS} = 10 \text{ V})^*$	$Q_{gd}$		12.2		nC
SOURCE-DRAIN DIODE CHARACTI	ERISTICS					
Forward On-Voltage(1)	$(I_S = 9A, V_{GS} = 0 V,$	V <sub>SD</sub>			1.5	V
Forward Turn-On Time		t <sub>on</sub>		**		ns
Reverse Recovery Time	$d_{IS}/d_t = 100A/\mu s)$	t <sub>rr</sub>		541.3		ns

<sup>\*</sup> Pulse Test: Pulse Width  $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$ 2%

<sup>\*\*</sup> Negligible, Dominated by circuit inductance



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### TYPICAL ELECTRICAL CHARACTERISTICS

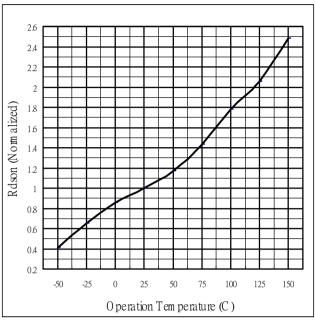


Fig 1. On-Resistance Vs. Temperature

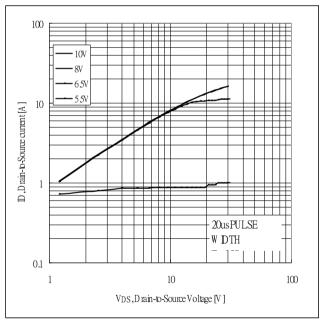


Fig 3. Typical Output Characteristics

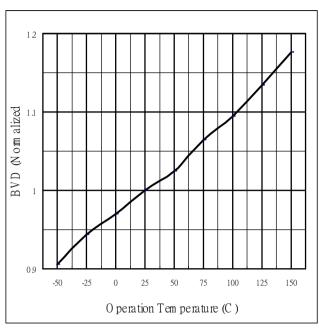


Fig.2 Breakdown Voltage Variation vs. Temperature

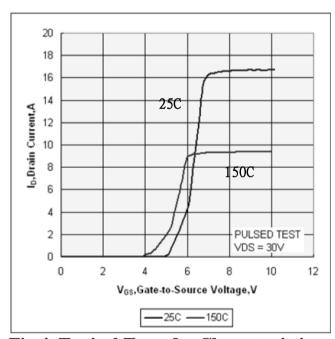


Fig 4. Typical Transfer Characteristics





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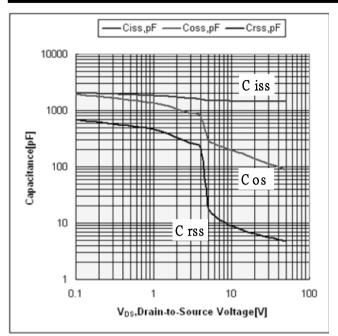


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

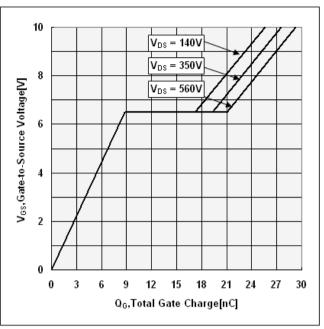


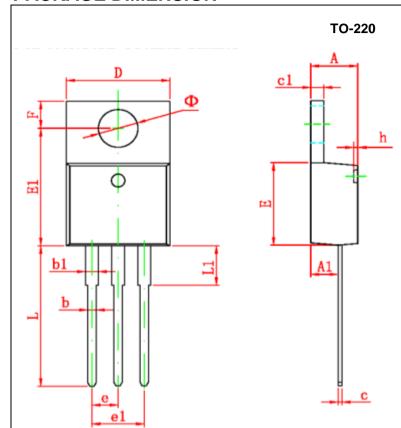
Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage





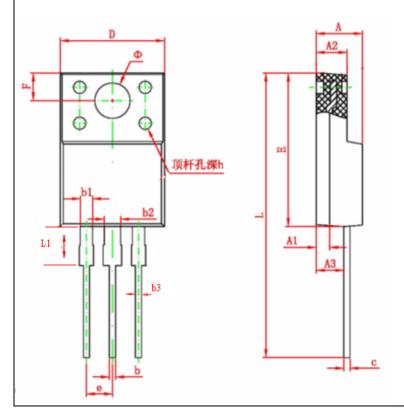
## Power Field Effect Transistor

### **PACKAGE DIMENSION**



C b - 1	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	4.40	4.80	
A1	2.10	2.84	
b	0.71	0.91	
b1	1.17	1.37	
С	0.30	0.60	
c1	1.17	1.47	
D	9.40	10.60	
E	8.40	9.60	
е	2.54 TYP.		
e1	4.90	5.60	
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	12.50	14.00	
L1	3.50	4.00	

### TO-220F



Cross le a l	Dimensions In Millimeters		
Symbol	Min.	Max	
А	3.80	4.70	
A1	1.3 REF.		
A2	2.20	3.20	
A3	2.10	3.20	
Ъ	0.30	0.95	
b1	1.00	1.75	
b2	1.00	1.75	
b3	0.50	0.80	
С	0.30	0.90	
D	9.90	10.40	
Е	14.60	16.20	
е	2.54 TYP.		
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	28.00	30.00	
L1	3.20	3 <b>.</b> 55	





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### **IMPORTANT NOTICE**

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